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Three Dimensional Modelling of Grain Boundary Interaction and Evolution During Directional Solidification of Multi-crystalline Silicon

T. Jain, H.K. Lin, C.W. Lan

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Evolution During Directional Solidification of Multi-crystalline Silicon**

T. Jain, H. K. Lin, C.W. Lan\*

Department of Chemical Engineering, National Taiwan University, Taipei, 10617, Taiwan

\*Corresponding author: [cwlan@ntu.edu.tw](mailto:cwlan@ntu.edu.tw); Tel.: 886-2-2363-3917

Fax: 886-2-2363-3917

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